

# **BF494 NPN RF Transistor**



# Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

1. Collector 2. Emitter 3. Base

Symbol	Parameter	Value	Unit	
V <sub>CEO</sub>	Collector-Emitter Voltage	20	V	
V <sub>CBO</sub>	Collector-Base Voltage	30	V	
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V	
I <sub>C</sub>	Collector Current - Continuous	30	mA	
TJ	Junction Temperature	150	°C	
T <sub>STG</sub>	Storage Temperature Range	- 55 ~ 150	°C	

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

### **Thermal Characteristics**

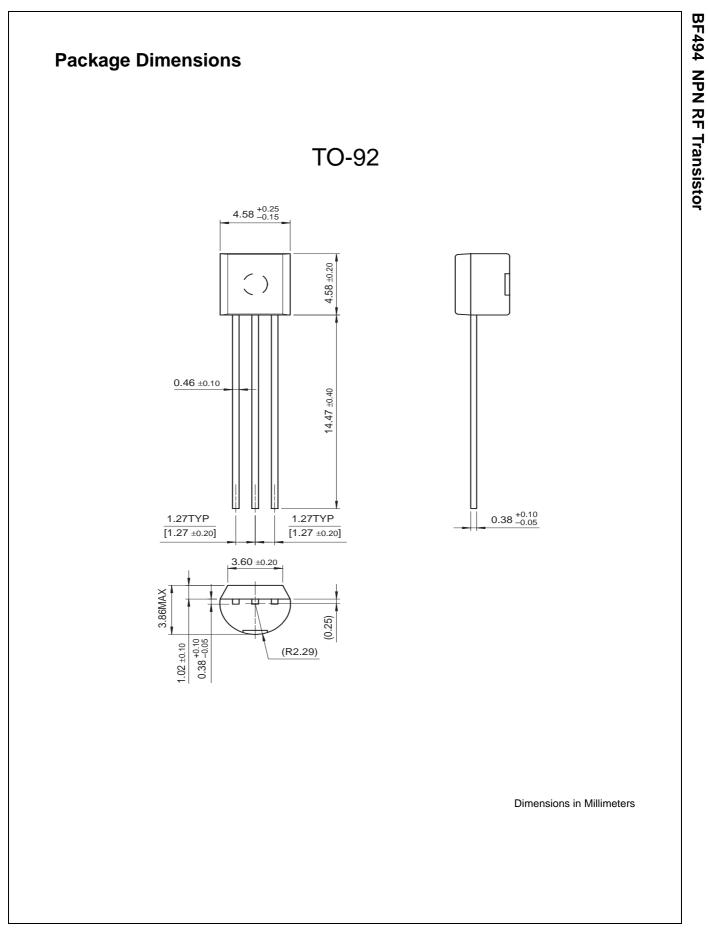
Symbol	Parameter	Value	Unit
P <sub>D</sub>	Total Device Dissipation, by R <sub>θJA</sub> Derate above 25°C	350 2.8	m₩ m₩/°C
$R_{\theta JC}$	Thermal Resistance, Junction to case	125	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

## Electrical Characteristics\* T<sub>c</sub> = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max.	Units
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0	20		V
V <sub>(BR)CBO</sub>	Collector-Base BreakdownVoltage	$I_{C} = 10 \mu A, I_{E} = 0$	30		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_{E} = 10 \mu A, I_{C} = 0$	5.0		V
I <sub>CES</sub>	Collector-Emitter Sustaining Current	$V_{CE} = 40V, V_{EB} = 0V$		10	nA
h <sub>FE</sub>	DC Current Gain	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1mA	67	222	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 5mA		0.2	V
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 5mA		0.92	V
V <sub>BE</sub> (ON)	Base-Emitter On Voltage	$V_{CE} = 10V, I_{C} = 10mA$	650	740	mV

\* DC Item are tested by Pulse Test: Pulse Width≤300us, Duty Cycle≤2%

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### **PRODUCT STATUS DEFINITIONS**

### **Definition of Terms**

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Rev. I20